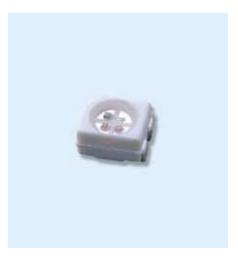




Features

- PLCC4 package.
- White package.
- Colorless clear window.
- Pb free
- RoHS compliant version.



Descriptions

- 120° viewing angle.
- Low power comsumption.

Applications

- Automotive: backlighting in dashboard and switch.
- Portable equipment.
- Flat backlight for LCD's, switches and symbols.
- General use.

Device Selection Guide

	Lens Color			
Туре	Type Material Emitted Color		Lens Color	
R6	AlGaInP	Brilliant Red		
GH	InGaN	Brilliant Green	Water Clear	
BH	InGaN	Blue		

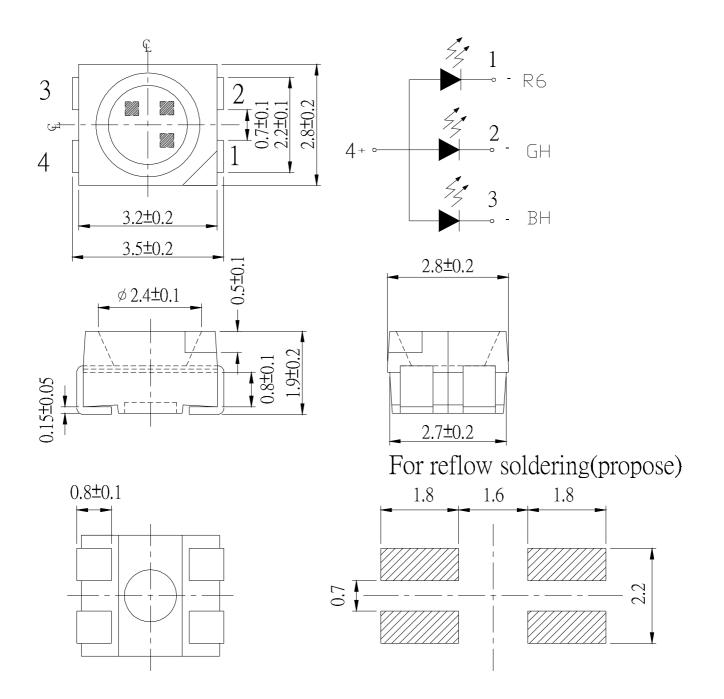








Package Outline Dimensions



Notes: All dimensions are in millimeters.





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Parameter	Symbol	Rating		Unit	
Reverse Voltage	Vr	5		V	
		R6	25		
Forward Current	IF	GH	25	mA	
		BH	25		
Operating Temperature	Topr		-4 0 ~ +85	°C	
Storage Temperature	Tstg		°C		
	ESD	R6	2000		
Electrostatic Discharge(HBM)		GH	150	V	
		BH	150		
	Pd	R6	120		
Power Dissipation		GH	110	mW	
		BH	110		
		R6	100		
Peak Forward Current(Duty 1/10 @ 1KHz)	Ifp	GH	100	mA	
		BH	100		
Soldering Temperature	Tsol	Reflow Soldering : 260 $^{\circ}$ C for 10 sec.			
		Hand Soldering : 350 $^{\circ}$ C for 3 sec.			

Absolute Maximum Ratings $(T_{a}=25^{\circ})$

Specific binning requirements- please contact our home office









Parameter	Symbol		Min.	Тур.		Unit	Condition
		R6	112		285	mcd	IF=20mA
Luminous Intensity	Iv	GH	180		450		
		BH	72		180		
		R6		632			
Peak Wavelength	λp	GH		518		nm	I =20mA
		BH		468			
		R6	621		631		
Dominant Wavelength	λd	GH	520		530	nm	IF=20mA
		BH	465		475		
C D. 1'	$ riangle \lambda$	R6		20		nm	IF=20mA
Spectrum Radiation Bandwidth		GH		35			
		BH		35			
		R6		2.0	2.4		
Forward Voltage	VF	GH		3.4	3.95	V	IF=20mA
		BH		3.4	3.95		
Viewing Angle	2 0 1/2			120		deg	IF=20mA
		R6			10		
Reverse Current	Ir	GH			50	μA	V _R =5V
		BH			50		

Electro-Optical Characteristics (Ta=25°C)

*The luminous intensity data did not including $\pm 10\%$ testing tolerance.







Chip	Bin	Min	Max	Unit	Condition
R6	R	112	180		IF=20mA
	S	180	285		
GH	S	180	285	mcd	
	Т	285	450		
BH	Q	72	112		
	R	112	180		

Bin Rang Of Luminous Intensity

Bin Rang Of Dominate Wavelength

Din Rung Of Dominate Wavelength							
Chip	Bin	Min	Max	Unit	Condition		
R6	FF1	621	626		I =20mA		
	FF2	626	631	nm			
GH	X	520	525				
	Y	525	530				
BH	X	465	470				
	Y	470	475				

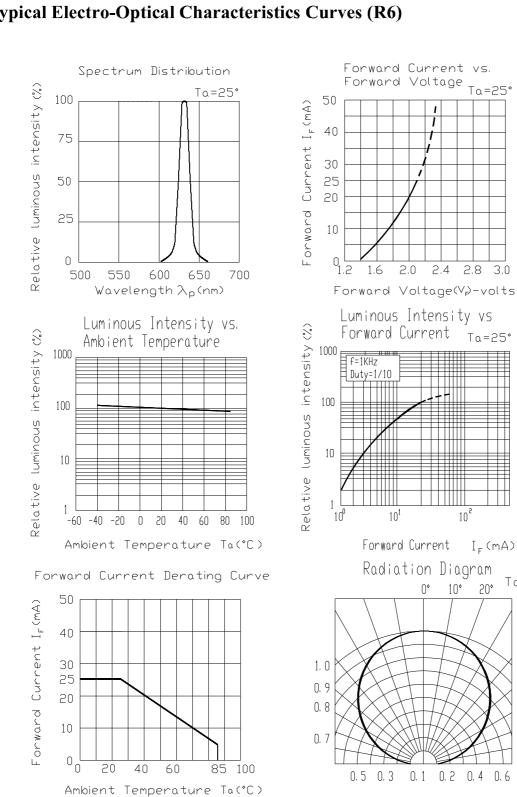
*The luminous intensity data did not including $\pm 10\%$ testing tolerance.





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Typical Electro-Optical Characteristics Curves (R6)

190 bosstick blvd, ste 101 san marcos, ca 92069 phone 760.560.1300 fax 760.560.1301

3.0

Ta=25°

30°

40°

50°

60°

70°

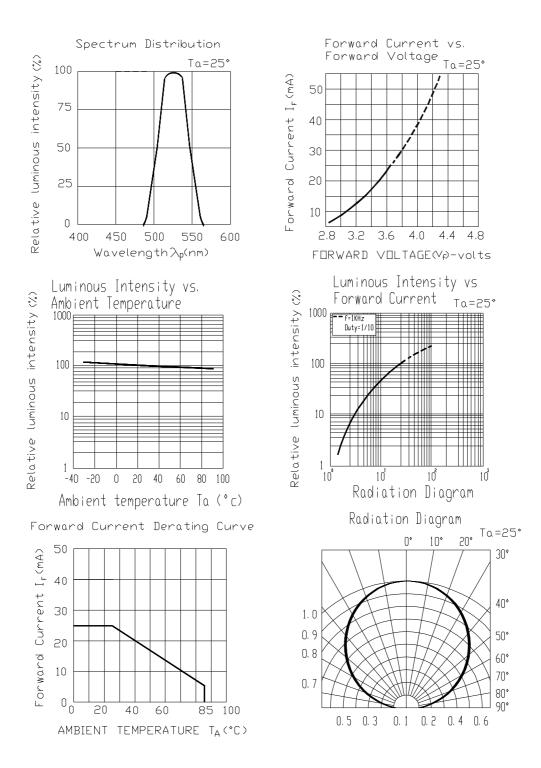
80°

90°

20*





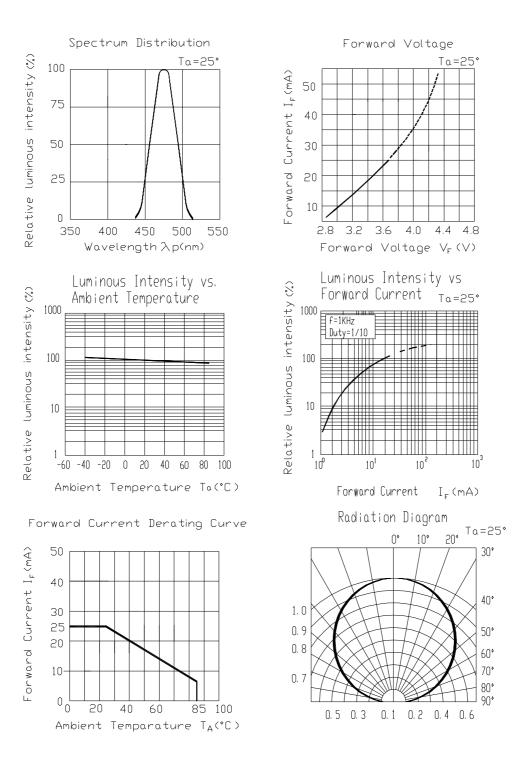


Typical Electro-Optical Characteristics Curves (GH)









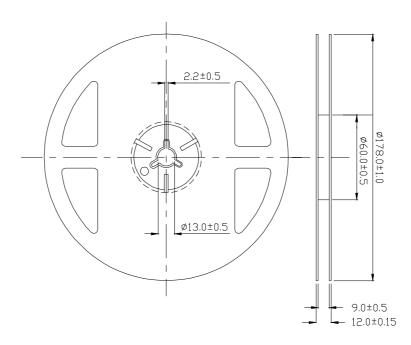
Typical Electro-Optical Characteristics Curves (BH)







Reel Dimensions



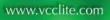
Note: Tolerances Unless Dimension ± 0.1 mm ,Unit = mm



PoHS

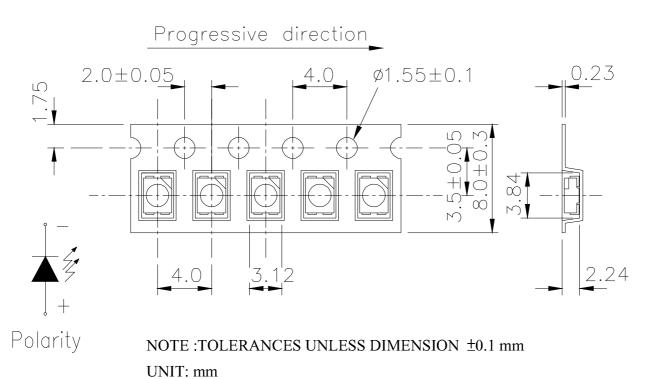
ISO 9001

Registered

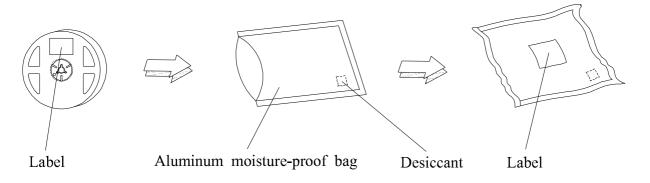




Carrier Tape Dimensions: Loaded quantity 2000 PCS per reel.



Moisture Resistant Packaging







Reliability Test Items And Conditions

The reliability of products shall be satisfied with items listed below.

Confidence level : 90%

LTPD: 10%

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1	Reflow Soldering	Temp. : 260°C ±5°C Min. 5sec.	6 Min.	22 PCS.	0/1
2	Temperature Cycle	H : +100°C 15min $\int 5 \text{ min}$ L : -40°C 15min	300 Cycles	22 PCS.	0/1
3	Thermal Shock	H:+100°C 5min $\int 10 \sec$ L:-10°C 5min	300 Cycles	22 PCS.	0/1
4	High Temperature Storage	Temp. : 100°C	1000 Hrs.	22 PCS.	0/1
5	Low Temperature Storage	Temp. : -40°C	1000 Hrs.	22 PCS.	0/1
6	DC Operating Life	$I_F = 20 \text{ mA}$	1000 Hrs.	22 PCS.	0/1
7	High Temperature / High Humidity	85°C/85%RH.	1000 Hrs.	22 PCS.	0/1
1	Reflow Soldering	Temp. : 260°C ±5°C Min. 5sec.	6 Min.	22 PCS.	0/1

190 bosstick blvd, ste 101 san marcos, ca 92069 **phone** 760.560.1300 **fax** 760.560.1301





OPTOELECTRONICS

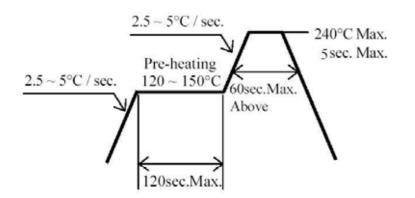


Precautions For Use

1. Customer must apply resistors for protection, otherwise a slight voltage shift will cause a big current change .

2. Storage

- 2.1 Do not open moisture proof bag before the products are ready to use
- 2.2 Before opening the package: The LEDs should be kept at 30° C or less and 90%RH or less.
- 2.3 After opening the package: The LED's floor life is 1 year under 30 deg C or less and 60% RH or less. If unused LEDs remain, it should be stored in moisture proof packages.
- 2.4 If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions. Baking treatment : $60\pm5^{\circ}$ C for 24 hours.
 - 3. Soldering Condition
 - 3.1 Pb free solder temperature profile



- 3.2 Reflow soldering should not be done more than two times.
- 3.3 When soldering, do not put stress on the LEDs during heating.
- 3.4 After soldering, do not warp the circuit board.

4.Soldering Iron

Each terminal is to go to the tip of soldering iron temperature less than 350° C for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.



